

10/617,726

L Number	Hits	Search Text	DB	Time stamp
1	1878	((438/678) or (438/687)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:27
2	1688	((((438/678) or (438/687)).CCLS.) and @ad<20021212	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:27
3	601	(((((438/678) or (438/687)).CCLS.) and @ad<20021212) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:27
4	510	(((((438/678) or (438/687)).CCLS.) and @ad<20021212) and electroless) and (copper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:28
5	441	((((((438/678) or (438/687)).CCLS.) and @ad<20021212) and electroless) and (copper cu)) and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:31
6	203	((((((438/678) or (438/687)).CCLS.) and @ad<20021212) and electroless) and (copper cu)) and etch\$3) and (gold au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:31
-	7342	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 16:27
-	6352	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.) and @ad<20021212	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:23
-	484	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.) and @ad<20021212) and (electroless adj plat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:24
-	412	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.) and @ad<20021212) and (electroless adj plat\$3)) and (copper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:24
-	342	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.) and @ad<20021212) and (electroless adj plat\$3)) and (copper cu)) and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:25
-	189	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.) and @ad<20021212) and (electroless adj plat\$3)) and (copper cu)) and etch\$3) and (gold au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:25
-	150	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.) and @ad<20021212) and (electroless adj plat\$3)) and (copper cu)) and etch\$3) and (gold au)) and (via through-hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:26
-	149	((29/874) or (29/829) or (29/830) or (29/846) or (29/852)).CCLS.) and @ad<20021212) and (electroless adj plat\$3)) and (copper cu)) and etch\$3) and (gold au)) and (via through-hole)) and (substrate board PCB PWB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/23 13:31